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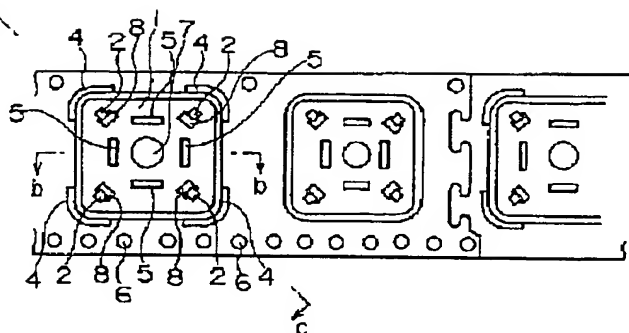
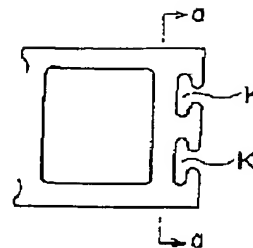
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APPLICANT : SUMITOMO BAKELITE CO LTD;

INVENTOR : HAMANO YOSHIO;

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TITLE : IC CHIP CARRIER TAPE AND
PRODUCTION THEREOF



ABSTRACT : PURPOSE: To accurately secure an IC chip in an IC chip storing cavity by a method wherein the rear end parts of injection molded carrier tape pieces having a plurality of IC chip storing cavity parts are fused together successively via the shaped parts in complementary engagement.

CONSTITUTION: A carrier tape piece is provided with a plurality of IC chip storing cavity parts and each cavity part is provided with the four seats 5 for mounting the IC chip thereon on its bottom 1 and a hole 7 for a pin for forcing out the IC chip in the center of the bottom 1. Molding sticks 2 are further provided vertically at the four corners inside the cavity part to hold the IC chip in place. The carrier tape piece is placed in a die up to an (a)-(a) line at its rear end, the die is closed, a molten resin is poured until it enters the cutout parts K at the rear end thereof, the molten resin is cooled and thereafter removed from the die and, by a connecting structure in a complementary engagement, the resins are connected together to obtain a carrier tape.

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